



TE Internal #: 2013022-1
 SO DIMM Sockets, Double Data Rate (DDR) 3, Stack Height .157 in [4 mm], Right Angle Module Orientation, 204 Position, .024 in [.6 mm] Centerline

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 3**
 Stack Height: **4 mm [.157 in]**
 Module Orientation: **Right Angle**
 Connector System: **Cable-to-Board**
 Number of Positions: **204**

Features

Product Type Features

DRAM Type	Double Data Rate (DDR) 3
Connector System	Cable-to-Board
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Bays	2
Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	204

Electrical Characteristics

DRAM Voltage	1.5 V
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Signal Characteristics

SGRAM Voltage	1.5 V
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Body Features



Ejector Location	Both Ends
Latch Material	Stainless Steel
Latch Plating Material	Tin
Module Key Type	SGRAM
Ejector Type	Locking
Connector Profile	Standard

Contact Features

Memory Socket Type	Memory Card
PCB Contact Termination Area Plating Material	Gold Flash
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold Flash
Contact Current Rating (Max)	.5 A

Termination Features

Insertion Style	Cam-In
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Mechanical Attachment

Mating Alignment Type	Standard Keying
PCB Mounting Style	Surface Mount
PCB Mount Retention	With
PCB Mount Retention Type	Solder Tail
Connector Mounting Type	Board Mount

Housing Features

Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	.6 mm [.024 in]

Dimensions

Stack Height	4 mm [.157 in]
Row-to-Row Spacing	8.2 mm [.322 in]

Usage Conditions

Operating Temperature Range	-55 – 85 °C [-67 – 185 °F]
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Operation/Application

Circuit Application	Power
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Industry Standards



UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	20
Packaging Method	Semi-Hard Tray Assembly

Other

Socket Connector Comment	Without floating peg.
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

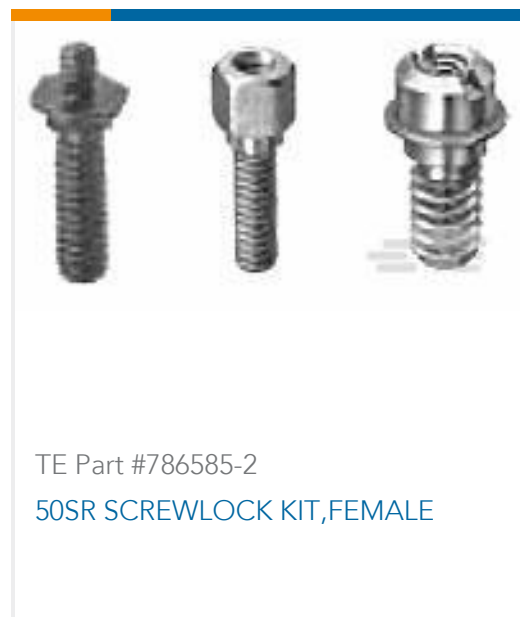
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Customers Also Bought



Documents

Product Drawings

[SEMI-HARD TRAY DDR3 204P 4H STD](#)

English

CAD Files

[Customer View Model](#)

[ENG_CVM_CVM_2013022-1_B.2d_dxf.zip](#)

English

[3D PDF](#)



3D

Customer View Model

[ENG_CVM_CVM_2013022-1_B.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2013022-1_B.3d_stp.zip](#)

English

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Datasheets & Catalog Pages

[DDR3 DIMM Sockets Flyer 6-1773454-7 05/09](#)

English

[6-1773457-3_DDR3_DIMM_SOCKETS](#)

Product Specifications

[Product Specification](#)

English

Product Environmental Compliance

[MD_2013022-1_072420181411_dmtec](#)

English

[MD_2013022-1_072420181411_dmtec](#)

English